



BGA
CSP
MCM

(Micro Screen is option)

Simple Ball Mounting Device BM-100V

The BM-100V is a machine for mounting ball terminals on BGA, CSP, MCM and other packages by using a microscreen (μ S-100series, option). Its applicability ranges from CSP with 30 pins to MCM with 3,000 pins for balls with a diameter of 0.28mm \varnothing to 0.89mm \varnothing . With the machine it is easy to mount ball terminals on a small quantity of packages when re-balling on reprocessed packages, or when mounting balls on newly developed chips, etc.

Features

- * Application range from CSP with 30 pins to BGA and MCM with 3,000 pins for balls with a diameter of 0.28mm \varnothing to 0.89mm \varnothing . (Depending on a microscreen selected for use with a package. The microscreen is optional.)
- * Flux/cream solder printing and ball mounting are possible with this single machine. (The user has to arrange for two types of screens: a screen for cream printing and a screen for ball mounting.)
- * The screen position (X, Y, Z) can be fine-adjusted with 10 μ m accuracy based on the micro meter.
- * Fixation of the package and the screen vertical movement are controlled automatically with the operating switch.
- * It is possible to carry out reflow-soldering immediately after ball alignment; a manual-type N₂ reflow machine RF-110N2 is also available. (Reflow jig for high temperature (290°C) solder ball can be also arranged for.)
- * The high resolution CCD camera with a zoom lens allows an easy positioning of the screen and the work. With the 5.8x to 17.8x zoom it is easy to handle positioning of packages even with large and microscopic patterns.

Specifications

- μ S-100series(option)
 - Size :From 14x28mm to 54x63mm (7 types)
 - Thickness :0.15mm (CSP 0.13mm)
 - Material :Frame SPCC
Screen SUS304
- Fine-adjustment of X, Y, Z :15mm (10 μ m steps)
- Dimensions/Mass

Main unit	(W)240x(D)325x(H)580mm	12kg
Control box	(W)180x(D)250x(H)110mm	3kg
Monitor TV	394x316x407mm	13kg
- Air input :2 to 5kgf/cm²
- Hose :OD6mm \varnothing xID4mm \varnothing
- CCD camera :350,000 pixels, 1/2 inch CCD
Display magnification: 5.8x to 17.8x zoom
- Monitor TV :14inch, flat cathode-ray tube
- Power source :AC120V or 220V 100VA 50/60Hz

Applicable package

- Size :From 6x6 to 50x50mm
- Number of pins :From 30 to 3,000 pins
- Pitch :1.5mm to 0.5mm
- Ball diameter :0.89mm \varnothing to 0.28mm \varnothing
- Soldering ball :183°C, 290°C

Options

- Micro Screen μ S-100series
- Manual reflow soldering equipment RF-110
RF-110N2
- Chip adsorption Stage Special order

Also please refer to the μ S-100series Catalogue.

* Specifications subject to change without notice.